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February 2014

ISL9R30120G2

30 A 1200 V STEALTH™ Diode

Features

- Stealth Recovery t_{rr} = 269 ns (@ I_F = 30 A)
- Max Forward Voltage, V_F = 3.3 V (@ T_C = 25°C)
- 1200 V Reverse Voltage and High Reliability
- · Avalanche Energy Rated
- · RoHS Compliant

Applications

- Switch Mode Power Supplies
- · Hard Switched PFC Boost Diode
- UPS Free Wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

Description

The ISL9R30120G2 is a STEALTH™ diode optimized for low loss performance in high frequency hard switched applications. The STEALTH™ family exhibits low reverse recovery current (I_{RR}) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low I_{RR} and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH™ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

Package JEDEC STYLE 2 LEAD TO-247 ANODE CATHODE (BOTTOM SIDE METAL) A A Symbol

Device Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Rating	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
V _{RWM}	Working Peak Reverse Voltage	1200	V
V _R	DC Blocking Voltage	1200	V
I _{F(AV)}	Average Rectified Forward Current (T _C = 80°C)	30	Α
I _{FRM}	Repetitive Peak Surge Current (20 kHz Square Wave)	70	Α
I _{FSM}	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60 Hz)	325	Α
P _D	Power Dissipation	166	W
E _{AVL}	Avalanche Energy (1 A, 40 mH)	20	mJ
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 175	°C
TL	Maximum Temperature for Soldering	300	°C
T_{PKG}	Leads at 0.063 in (1.6 mm) from Case for 10 s Package Body for 10s, See Application Note AN-7528	260	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Part Number Top Mark		Top Mark	Package	Packing Method	Tape V	Vidth	Quar	ıtity
ISL9R30120G2 R30120G2		TO-247	Tube	N/A		30		
lectric	cal Chara	acteristics T _C = 25	°C unless otherwi	se noted				
Symbol	Parameter		Test Conditions		Min	Тур	Max	Unit
ff State	Characte	ristics						
I _R	Instantaneous Reverse Current		V _R = 1200 V	T _C = 25°C	-	-	100	μA
				T _C = 125°C	-	-	1.0	mA
n State	Characte	ristics						
V _F	Instantaneo	us Forward Voltage	I _F = 30 A	T _C = 25°C	_	2.8	3.3	V
•		· ·	i i	T _C = 125°C	-	2.6	3.1	V
ynamic	Characte	ristics						
СЛ	Junction Ca	pacitance	V _R = 10 V, I _F =	= 0 A	-	115	-	pF
witchin	g Charact	eristics				•		
t _{rr} Reverse Recovery Time		covery Time	$I_F = 1 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, V}_R = 15 \text{ V}$		-	45	56	ns
			$I_F = 30 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, V_R = 15 \text{ V}$		-	80	100	ns
t _{rr}	Reverse Re	covery Time	I _F = 30 A,		-	269	-	ns
Irr	Reverse Recovery Current		$dI_F/dt = 200 \text{ A/µs},$		-	7.5	-	Α
Q_{rr}	Reverse Re	covered Charge	$V_R = 780 \text{ V}, T_C = 25^{\circ}\text{C}$			930	-	nC
t _{rr}	Reverse Re	covery Time	I _F = 30 A, dI _F /dt = 200 A/μs, V _R = 780 V, T _C = 125°C		-	529	-	ns
S	Softness Fa	ictor (t _b /t _a)			-	6.2	-	-
I _{rr}	Reverse Re	covery Current			-	11	-	Α
Q _{rr}	Reverse Re	covered Charge	1C = 120 C			3.0	-	μC
t _{rr}	Reverse Re	covery Time	$I_F = 30 \text{ A},$ $dI_F/dt = 1000 \text{ A/}\mu\text{s},$		-	260	-	ns
S	Softness Fa	ictor (t _b /t _a)			-	4.8	-	-
I _{rr}	Reverse Re	covery Current	V _R = 780 V, T _C = 125°C			30	-	Α
Q _{rr}	Reverse Re	covered Charge				3.4	-	μC
dI _M /dt	Maximum d	i/dt during t _b				520	-	A/µ:
hermal	Characte	ristics				_		
$R_{\theta JC}$	Thermal Re	sistance Junction to Cas	ase TO-247			-	0.75	°C/V
	Thermal Resistance Junction to Ambient TO-247						°C/V	

Typical Performance Curves

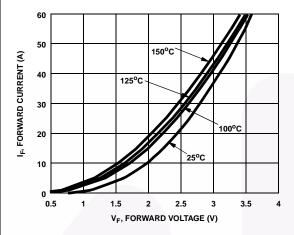


Figure 1. Forward Current vs Forward Voltage

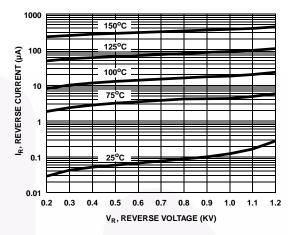


Figure 2. Reverse Current vs Reverse Voltage

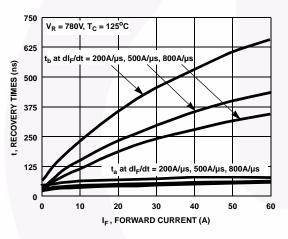


Figure 3. t_a and t_b Curves vs Forward Current

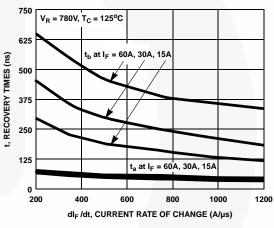


Figure 4. t_a and t_b Curves vs dl_F/dt

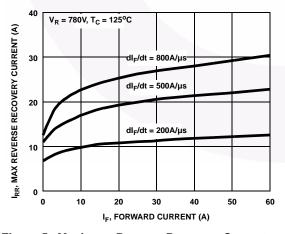


Figure 5. Maximum Reverse Recovery Current vs
Forward Current

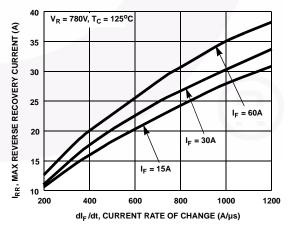


Figure 6. Maximum Reverse Recovery Current vs dI_F/dt

Typical Performance Curves (Continued) 9 V_R = 780V, T_C = 125°C V_R = 60A I_F = 30A I_F = 15A

Figure 7. Reverse Recovery Softness Factor vs dI_F/dt

dI_F/dt, CURRENT RATE OF CHANGE (A/μs)

800

600

200

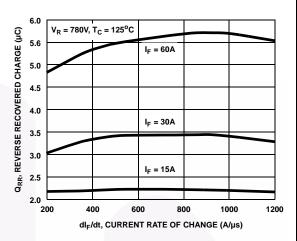


Figure 8. Reverse Recovery Charge vs dl_F/dt

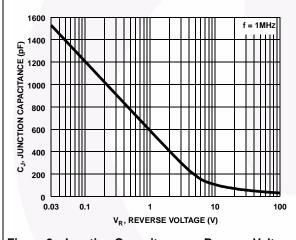


Figure 9. Junction Capacitance vs Reverse Voltage

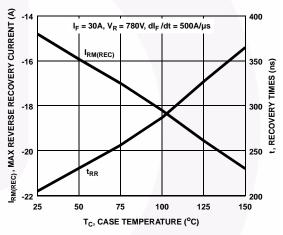
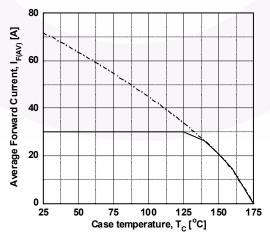


Figure 10. Maximum Reverse Recovery Current and t_{rr} vs Case Temperature



1200

Figure 11. DC Current Derating Curve

Typical Performance Curves (Continued)

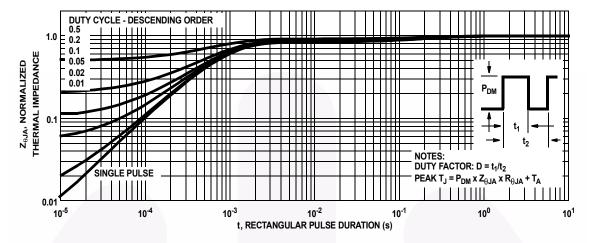
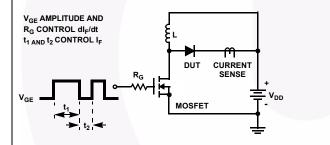


Figure 12. Normalized Maximum Transient Thermal Impedance

Test Circuit and Waveforms



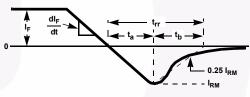
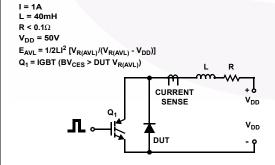


Figure 13. t_{rr} Test Circuit

Figure 14. t_{rr} Waveforms and Definitions



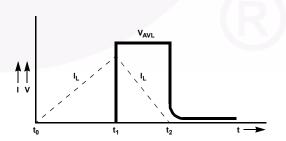
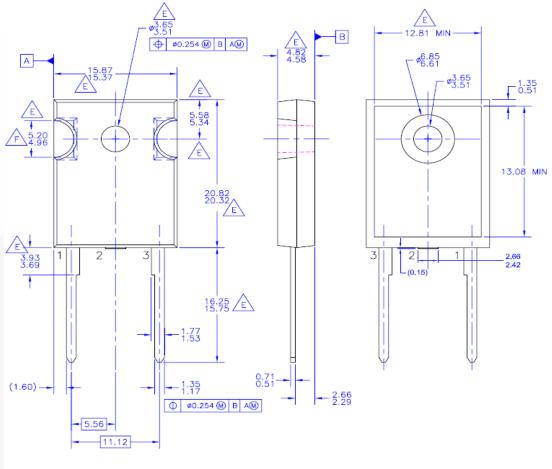


Figure 15. Avalanche Energy Test Circuit

Figure 16. Avalanche Current and Voltage Waveforms

Mechanical Dimensions

TO-247 2L



NOTES: UNLESS OTHERWISE SPECIFIED

- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
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- D. DRAWING CONFORMS TO ASME Y14,5 1994
- E. DOES NOT COMPLY JEDEC STANDARD VALUE
- F. NOTCH MAY BE SQUARE
- G. DRAWING FILENAME: MKT-TO247B02_REV02

Figure 17. TO-247, Molded, 2LD, Jedec Option AB

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